Product/Process Change Notice - PCN 23_0004 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Assembly Site Transfer of Select PBGA Products to ASE Kaohsiung (AEG)
Publication Date:	08-Mar-2023
Effectivity Date:	10-Jun-2023 *(the earliest date that a customer could expect to receive changed material)*
Revision Description:	Initial Release

Description Of Change:

1) Assembly site for selected (23x23) and (27x27) PBGA parts are moving from ASE Chungli Taiwan (AET) to ASE Kaohsiung Taiwan (AEG).
2) Change in Die attach material from Ablestik 2100A to Ablestik 2100AC.

Existing qualified Bill of Material (BOM) in AEG will be used.

Reason For Change:

ASE Chungli Taiwan (AET) issued a discontinuance notice to ADI to close their 23x23mm and 27x27mm PBGA products assembly by April, 2023. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, materials, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from different manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability:

No impact on form, fit and function or reliability.

Product Identification *(this section will describe how to identify the changed material)*

Parts assembled at AEG will be identified by Assembly Lot number and Date Code.

Summary of Supporting Information:

Qualification will be performed per Industry Standard Test Methods. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan

ADI_PCN_23_0004_Rev_-_Qualification Plan Summary for 23x23 PBGA at ASE...

Attachment 2: Type: Qualification Plan

ADI_PCN_23_0004_Rev_-_Qualification Plan Summary for 27x27 PBGA at ASE...

Attachment 3: Type: Detailed Change Description

ADI_PCN_23_0004_Rev_-_Material Set AET to AEG PBGA Transfer.pdf...

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models:

Added Parts On This Revision - Product Family / Model Number (8)

ADSP-21060L / ADSP-21060LABZ-160	ADSP-21061L / ADSP-21061LKBZ-160	ADSP-21160M / ADSP-21160MKBZ-80	ADSP-21160N / ADSP-21160NCBZ-100	ADSP-BF561 / ADSP-BF561SBBZ500
ADSP-BF561 / ADSP-BF561SKBZ600	ADSP-TS101S / ADSP-TS101SAB1Z000	ADSP-TS101S / ADSP-TS101SAB1Z100		

ANALOG DEVICES

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Assembly Site Transfer of Select PBGA Products to ASE Kaohsiung (AEG)

BOM Change Summary

- ADSP-21060L, ADSP-21061L and ADSP-21160M

Assembly Site	ASE Chungli Taiwan – AET (From)	ASE Kaohsiung Taiwan – AEG (To)
Wire	Au / 1.2 mil	Au / 1.2 mil
Die Attach	AB-2100A Conductive	AB-2100AC Conductive
Mold Compound	Hitachi CEL-9750	Hitachi CEL-9750
Ball Size	0.75	0.75
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu

BOM Change Summary

- ADSP-21160N

Assembly Site	ASE Chungli Taiwan – AET (From)	ASE Kaohsiung Taiwan – AEG (To)
Wire	Au / 1.0 mil	Au / 1.0 mil
Die Attach	AB-2100A Conductive	AB-2100A Conductive
Mold Compound	Hitachi CEL-9750	Hitachi CEL-9750
Ball Size	0.75	0.75
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu

BOM Change Summary

- ADSP-BF561

Assembly Site	ASE Chungli Taiwan – AET (From)	ASE Kaohsiung Taiwan – AEG (To)
Wire	Au / 1.0 mil	Au / 1.0 mil
Die Attach	AB-2100A Conductive	AB-2100AC Conductive
Mold Compound	Hitachi CEL-9750	Hitachi CEL-9750
Ball Size	0.6	0.6
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu

BOM Change Summary

- ADSP-TS101S

Assembly Site	ASE Chungli Taiwan – AET (From)	ASE Kaohsiung Taiwan – AEG (To)
Wire	Au / 1.2 mil	Au / 1.2 mil
Die Attach	AB-2100A Conductive	AB-2100AC Conductive
Mold Compound	Hitachi CEL-9750	Hitachi CEL-9750
Ball Size	0.6	0.6
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu

Appendix B - Revision History:			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	08-Mar-2023	10-Jun-2023	Initial Release

Assembly Site Transfer of Select PBGA Products to ASE Kaohsiung (AEG)

Qualification Plan Summary for 23x23mm PBGA at AEG

QUALIFICATION PLAN			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**EXPECTED COMPLETION DATE**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 32	Apr 2023
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	Apr 2023
High Temperature Storage Test (HTS)	JEDEC *JESD22-A103*	1 x 32	Apr 2023
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC *JESD22-A118*	3 x 32	Apr 2023

* Preconditioned per JEDEC/IPC J-STD-020.

Assembly Site Transfer of Select PBGA Products to ASE Kaohsiung (AEG)

Qualification Plan Summary for 27x27mm PBGA at AEG

QUALIFICATION PLAN			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**EXPECTED COMPLETION DATE**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 32	June 2023
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	June 2023
High Temperature Storage Test (HTS)	JEDEC *JESD22-A103*	1 x 32	June 2023
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC *JESD22-A118*	3 x 32	June 2023
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	3 x 32	June 2023

* Preconditioned per JEDEC/IPC J-STD-020.